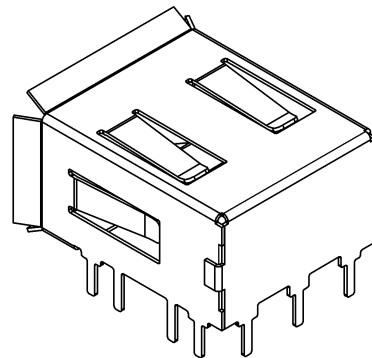
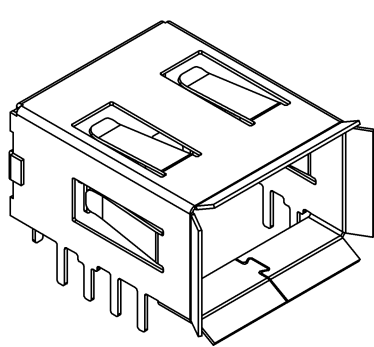
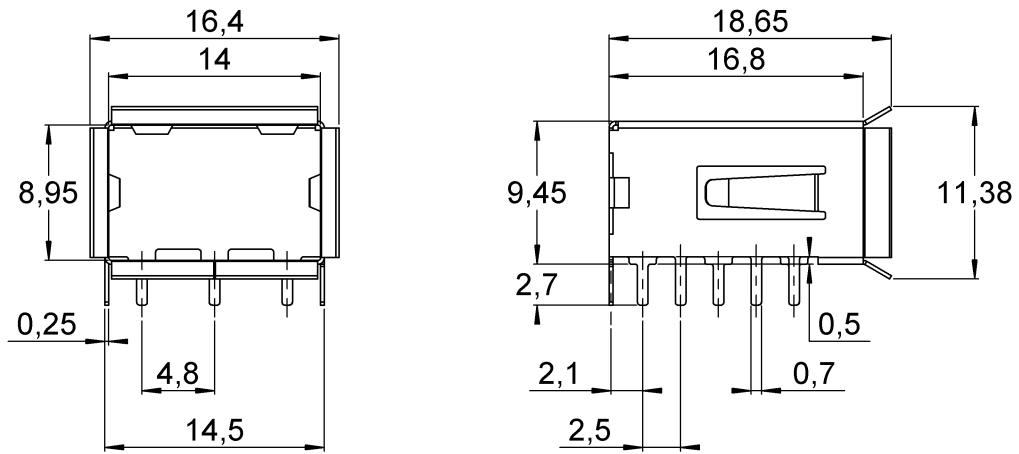


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|----------|-----------------|--------------|------------------------|
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All dimensions are in mm.

**DESCRIPTION**

| REP | COMPONENT          | MATERIALS | PLATING |
|-----|--------------------|-----------|---------|
| 1   | SFP Shielding cage | BRASS     | NiSn    |

|          |                 |              |                        |
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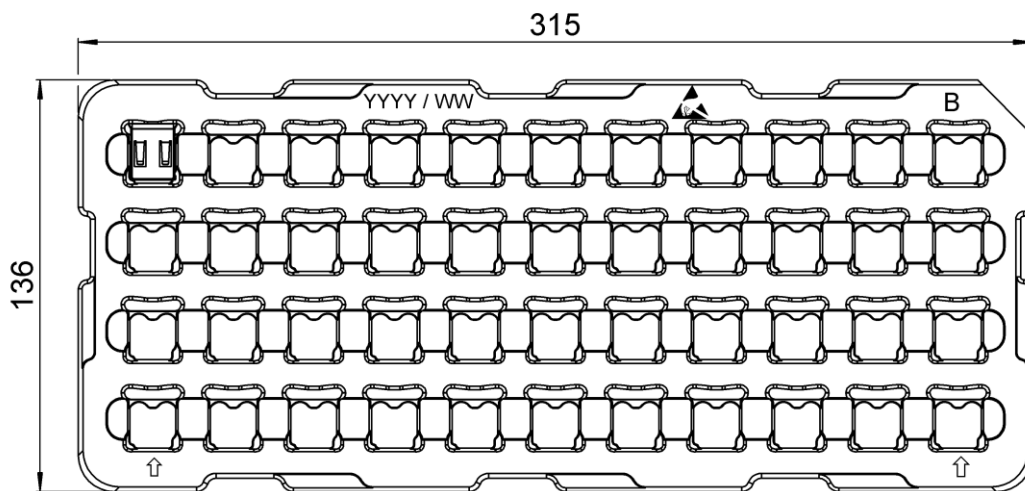
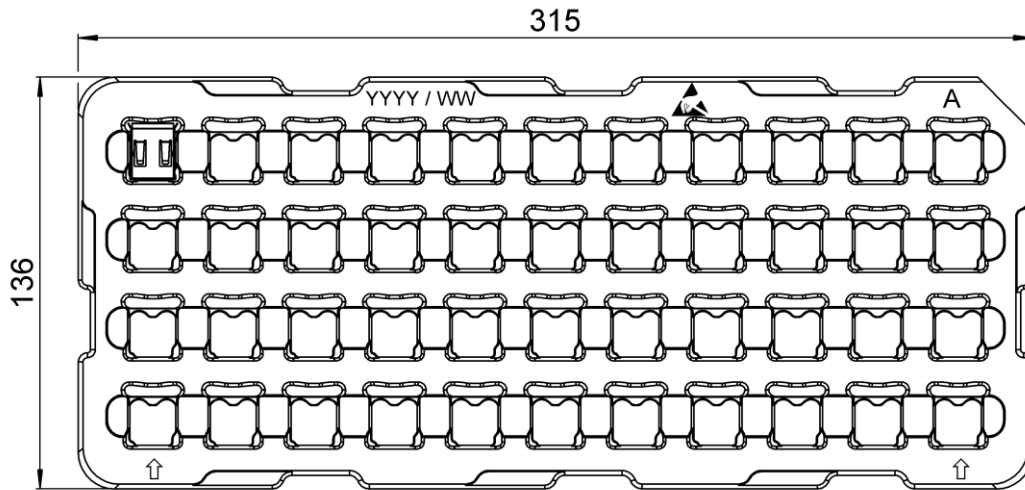
**GENERAL CHARACTERISTICS**


|  |  |   |
|--|--|---|
| <b>Mechanical</b><br>Mating endurance (cycles)<br>Vibration<br>Weight (g)                              | IEC 61300-2-2<br>IEC 61300-2-1<br>-            | 100<br>-<br>1,6530                        |
| <b>Environmental</b><br>Operating temperature (°C)<br>Storage temperature (°C)<br>RoHS<br>Flammability | IEC 61300-2-22<br>IEC 61300-2-22<br>-<br>UL 94 | -40 / +85<br>-40 / +85<br>Compliant<br>V0 |
| <b>Others</b><br>-<br>Handling   | -<br>-   | ESD approved<br>Only with gloves          |

|          |                 |              |                        |
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**PACKAGING:**

Packaging in Hot Formed Tray

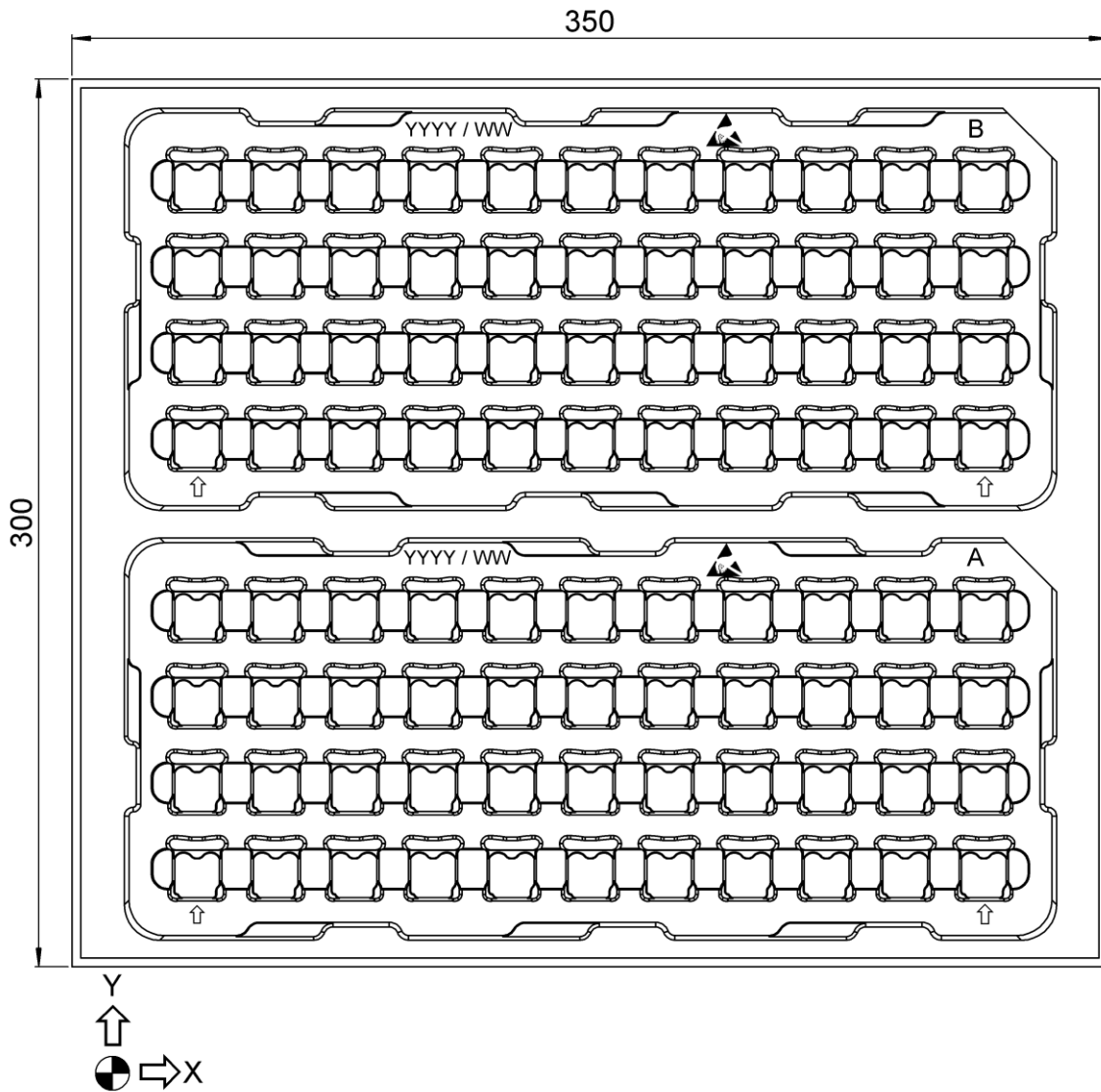


**Tray Information:**  
 44 pcs by Tray  
 Color: tray A in black and tray B in translucent  
 YYYY: manufacturing year  
 WW: manufacturing week  
: ESD symbol

|          |                 |              |                        |
|----------|-----------------|--------------|------------------------|
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**PACKAGING:**

Packaging in the box

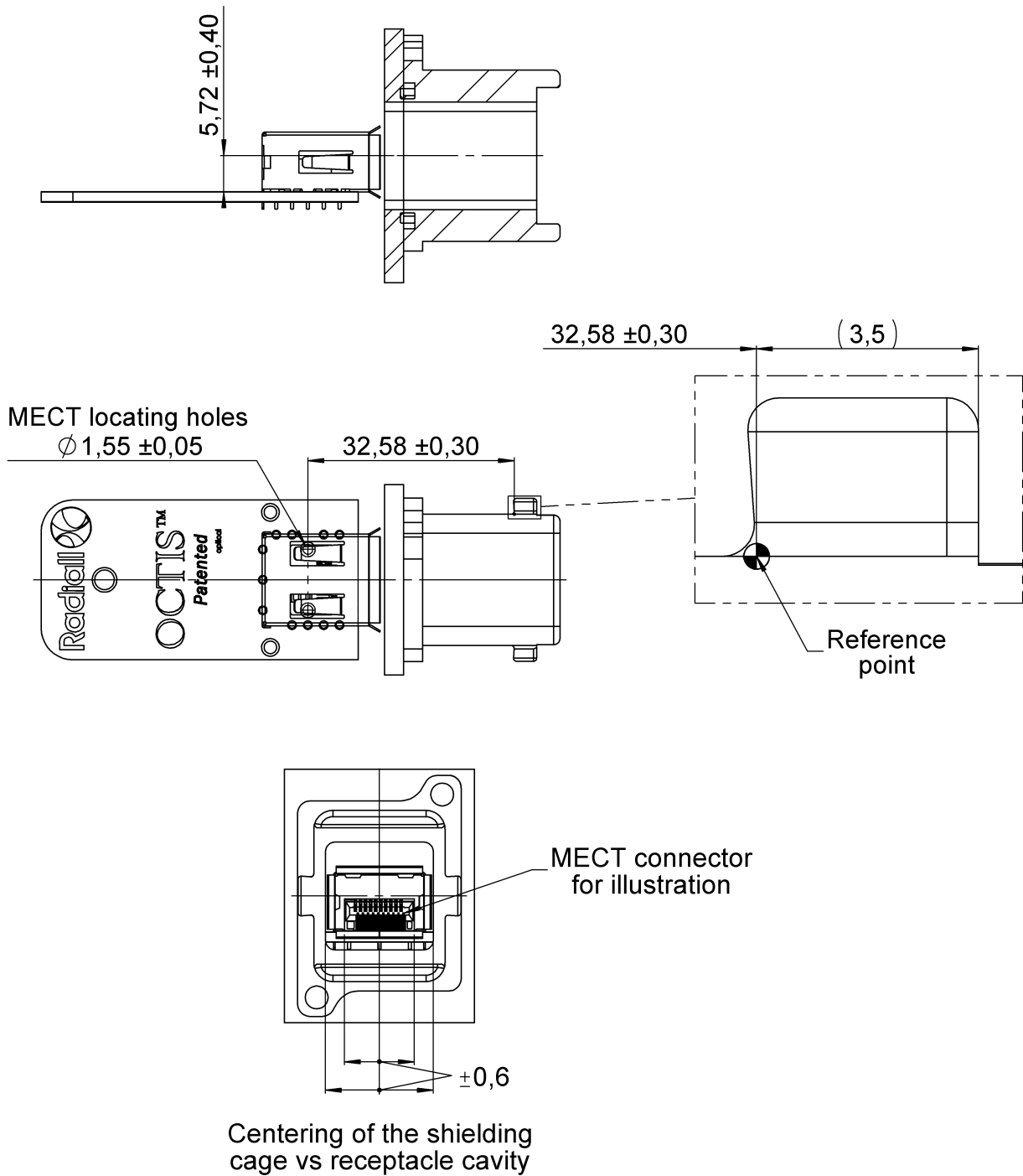


**Packaging Information:**  
 1144 pcs by Box  
 X pitch = 26.6 mm  
 Y pitch = 26.6 mm  
 Z dimension = 18 mm  
 Tray A and tray B stocked alternatively  
 Hot formed trays fitted in a ESD bag  
 and in card board box

|          |                 |              |                        |
|----------|-----------------|--------------|------------------------|
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**POSITIONNING AND PATTERN DEFINITION**

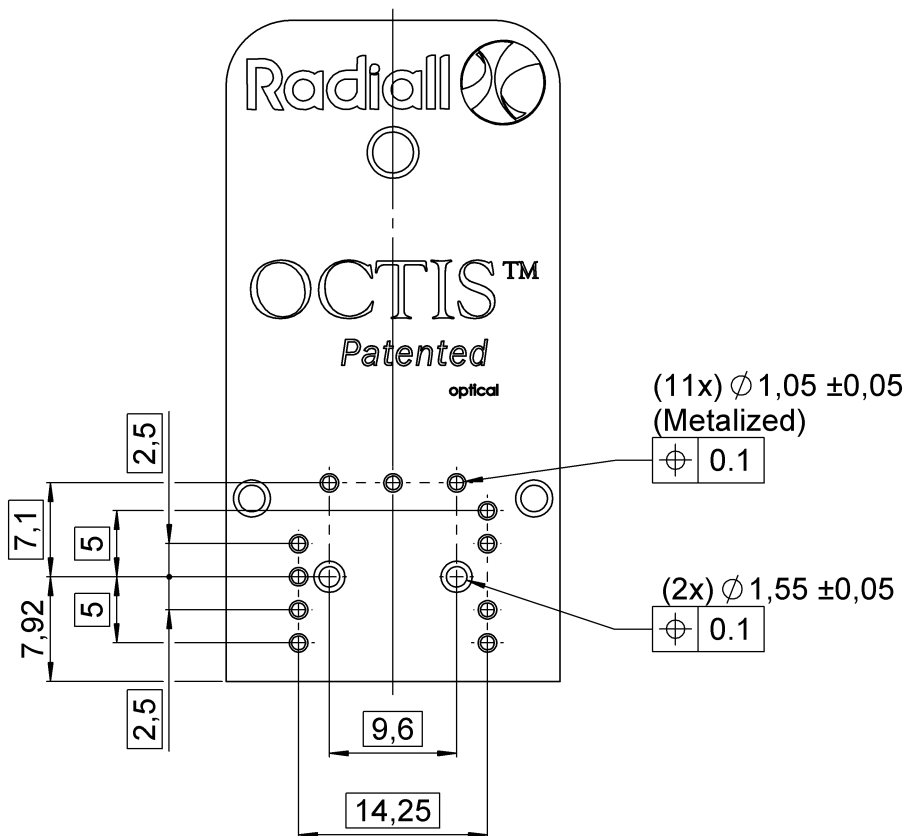
**OCTIS SFP Version with universal receptacle**



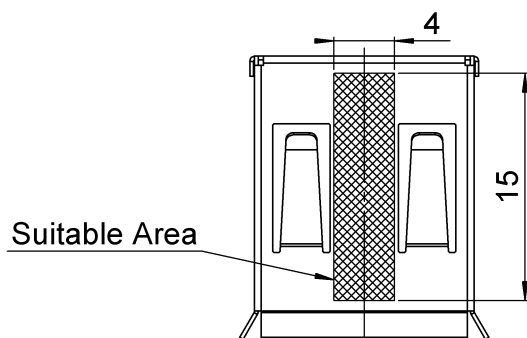
For use with OCTIS Plug Kit p/n OCTI.117.500

|          |                 |              |                        |
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**FOOT/PRINT**  
(General Tolerances for PCB +/- 0,1 mm)



**SUITABLE AREA FOR PICK & PLACE VACUUM NOZZLE**



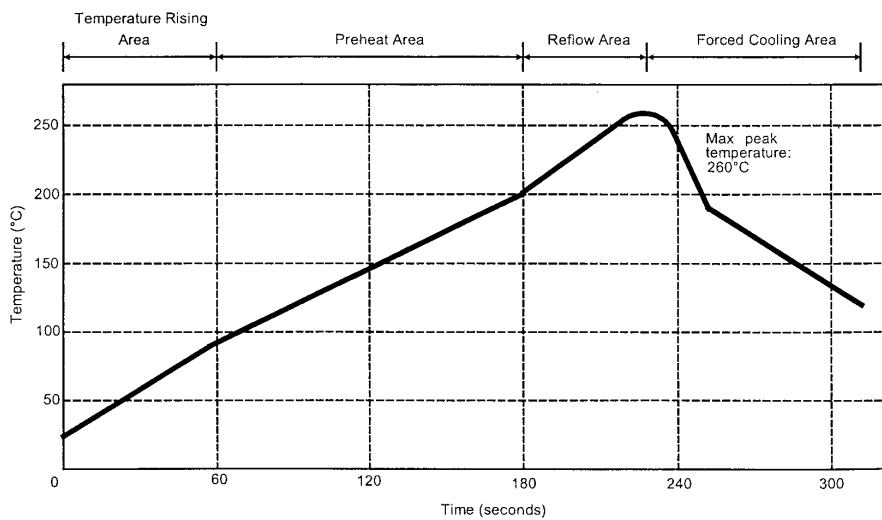
|          |                 |              |                               |
|----------|-----------------|--------------|-------------------------------|
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|----------|-----------------|--------------|-------------------------------|

## SOLDER PROCEDURE\*

1. Deposit solder paste (Sn Ag4 Cu0.5) on solder pads / mounting area by screen printing application. We recommend a low residue flux. Verify that the edges of the pads are clean.
2. Place the component on the mounting area with a pick & place machine. A video camera is recommended for a good positioning of the component. Adhesive agents must not be used on the component.
3. This process of soldering has been tested with a convection oven. Below please find the typical soldering profile to use.
4. Optional cleaning of printed circuit board.
5. Check solder joints and position of the component by visual inspection.

Note: When soldering a receptacle, no plug should be mated to the receptacle before completion of this procedure.

### TEMPERATURE PROFILE



| Parameter                        | Value    | Unit   |
|----------------------------------|----------|--------|
| Temperature rising Area          | 1 to 4   | °C/sec |
| Max Peak Temperature             | 260      | °C     |
| Max dwell time @260°C            | 10       | sec    |
| Min dwell time @235°C            | 20       | sec    |
| Max dwell time @235°C            | 60       | sec    |
| Temperature drop in cooling Area | -1 to -4 | °C/sec |
| Max dwell time above 100°C       | 420      | sec    |

\*Typical data for reflow process. Alternatively, wave soldering is also possible